



Automatic Wafer Inspection System

MODEL IV-W2000

Automatic inspection machine for Wafer defects designed for Semicon backend manufacturing.

Ergonomic, compact and space saving design.



Key Features

- Automatic Wafer Handling of Wafer after Saw Process
- Automatic Alignment of Wafer before Inspection
- Inspects Sawed and Unsawed 6; 8; 12 inches Full and Partial Wafer or Wafer by Region
- WPH < 3 mins Full Inspection < 2um Resolution
- Software Rotated eMap Display
- Customized eMap Configuration
- Manual Review of Inspection Result
- User Defined Reject Bin Code
- Touch Screen Monitor for Easy Operation
- SECS/GEM Communication